

Ultra-Low Capacitance ESD Diode Array

- Rail-to-rail diodes with internal TVS diode
- ESD / transient protection of four I/O lines and one Vcc line exceeding:

IEC61000-4-2 (ESD): ± 15 kV (contact)

IEC61000-4-4 (EFT): 2.5 kV / 50 A (5/50 ns)

IEC61000-4-5 (surge): 3 A (8/20 μs)

- Reverse working voltage data lines: 5.3 V max.
- Reverse working voltage Vcc: 6 V max.
- Very low capacitance: 0.4 pF typ.
- Very low reverse current < 10 nA typ.
- Very low clamping voltage:
 - 12 V typ. at positive transients
 - 4 V typ. at negative transients
- Pb-free (RoHS compliant) package

Applications

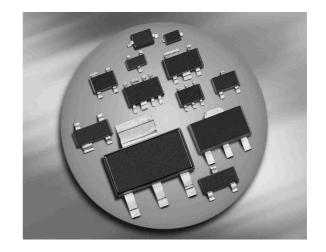
- USB 2.0 ports and future USB 3.0 ports
- Ethernet port: 10/100/1000 Mb/s
- IEEE 1394 FireWire ports
- Mobile communications e.g. high-speed SIM card protection
- Consumer products (STB, DVD, DSC, DVC...)
- Notebooks and desktop computers, peripherals



ESD5V3U4RRS



Туре	Package	Configuration	Marking
ESD5V3U4RRS	SOT363	6 pins, uni-directional	E8s





Maximum Ratings at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit
ESD contact discharge ¹⁾	V _{ESD}	15	kV
Peak pulse current $(t_p = 8 / 20 \mu s)^2)$	I _{pp}	3	Α
Peak pulse power $(t_p = 8 / 20 \mu s)^2$	P_{pk}	50	W
Operating temperature range	T_{op}	-55125	°C
Storage temperature	T _{stg}	-65150	

Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics ³⁾	•				•
Reverse working voltage	V_{RWM}				V
I/O pin ⁴⁾ to pin 5		-	-	5.3	
pin 2 to pin 5		-	-	6	
Breakdown voltage	V _(BR)	6.3	-	-	
$I_{(BR)}$ = 1 mA, any pin to pin 5					
Reverse current	I _R	-	< 10	100	nA
V_{R} = 5.3 V, any pin to pin 5					
Clamping voltage	V_{CL}				V
I_{PP} = 1 A, t_p = 8/20 µs ²⁾ , any pin to pin 5		-	10	13	
$I_{PP} = 3 \text{ A}, t_p = 8/20 \mu\text{s}^{2)}, \text{ any pin to pin 5}$		-	12	15	
Forward clamping voltage	V_{FC}				
$I_{PP} = 1 \text{ A}, t_p = 8/20 \ \mu\text{s}^{2}$, any pin to pin 5		_	2	4	
$I_{PP} = 3 \text{ A}, \ \dot{t}_{p} = 8/20 \ \mu\text{s}^{2}, \text{ any pin to pin 5}$		-	4	6	
Line capacitance ⁵⁾⁴⁾	C _T	-	0.4	0.6	pF
V_R = 0 V, f = 1 MHz, any I/O pin to pin 5					
Dynamic resistance ⁶⁾	R_{D}	-	-	-	-

 $^{^{1}}V_{\mathrm{ESD}}$ according to IEC61000-4-2

 $^{^2}I_{\rm pp}$ according to IEC61000-4-5

³It is strongly recommended that pin 5 is connected to ground for propper functionality.

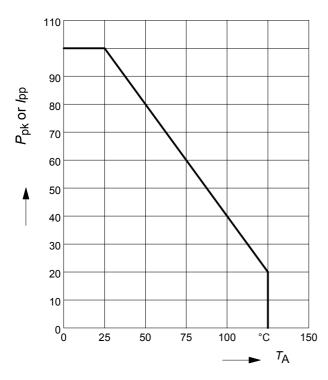
⁴I/0 pins are pin 1, 3, 4, 6

⁵Total capacitance line to ground

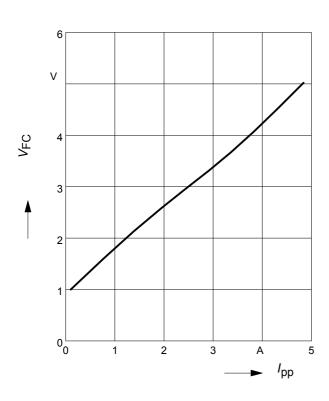
⁶ according to TLP tests



Power derating curve $P_{pk} = f(T_A)$

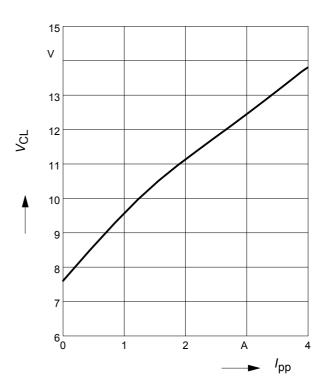


Forward clamping voltage $V_{\rm FC}$ = $f(I_{\rm PP})$ $t_{\rm p}$ = 8 / 20 $\mu {\rm s}$



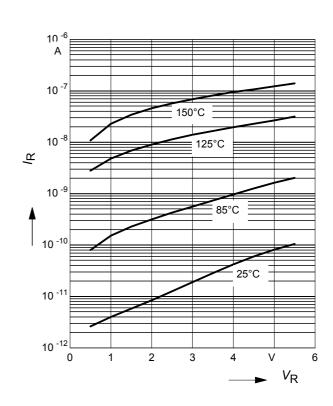
Clamping voltage, $V_{cl} = f(I_{pp})$

$$t_{\rm p}$$
 = 8 / 20 $\mu {\rm s}$



Reverse current $I_R = f(V_R)$

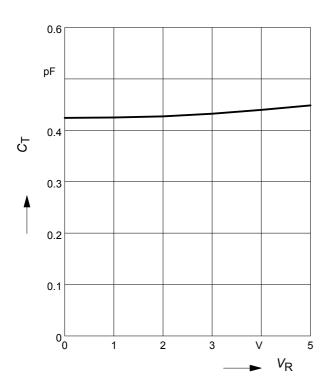
$$T_A$$
 = Parameter





Diode capacitance $C_T = f(V_R)$

f = 1MHz

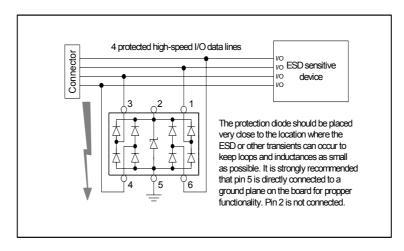


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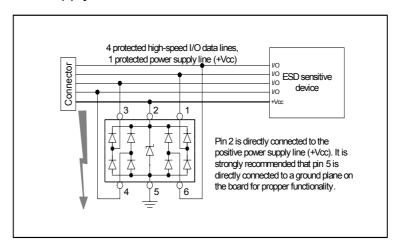
Application example ESD5V3U4RRS

4 data lines, uni-directional



Application example ESD5V3U4RRS

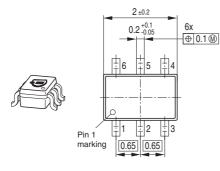
4 data lines and 1 power supply line, uni-directional

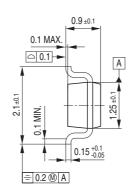


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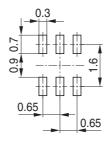


Package Outline



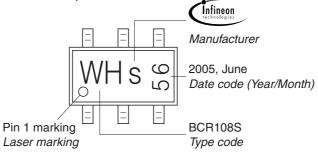


Foot Print



Marking Layout (Example)

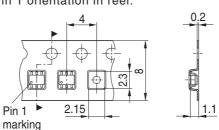
Small variations in positioning of Date code, Type code and Manufacture are possible.



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.



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